



DXB Wafer Bonder

The DXB is used for bonding wafers to temporary substrates for subsequent wafer processing.

Applications

- Wafer Lapping
- Wafer Polishing
- Wafer Dicing
- Any other temporary wafer bonding process



- DXB provides a controlled bonding environment with even heat and constant pressure in an air-evacuated chamber for bonding semiconductor materials to disposable and reusable substrates.

- DXB is designed to bond wafers using **WaferGrip Temporary Adhesive**. Dynatex International supplies WaferGrip in various preformed shapes and sizes to suit the required application. This along with the accurately controlled bond line provides an efficient and robust process.

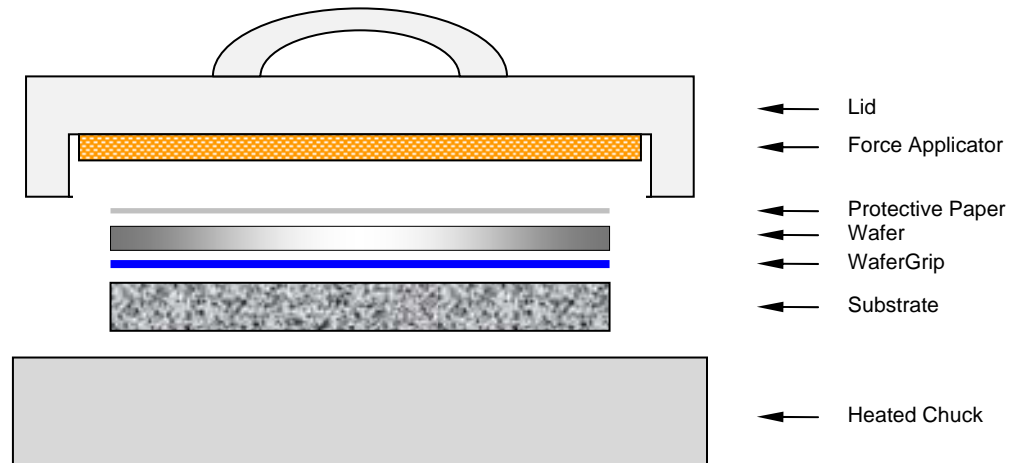


WaferGrip Temporary Adhesive Preforms

- DXB bonding chamber is available in two sizes: 11 inches (279 mm) and 5.2 inches (132 mm). The DXB can be used for single or multiple wafer bonding. For example, four four inch wafer can be bonded at one time..

Bonding a Wafer

When bonding a wafer, the lid of the bonder is removed and the mounting substrate, adhesive, wafer and protective paper are set onto the heated chuck. The lid to the bonder is then placed back on and the cycle button is pressed. The bonder then evacuates the air from the chamber, applies the programmed amount of force for the programmed length of time, bonding the wafer to the substrate.



DXB Wafer Bonder

The diagram shows the wafer bonder chuck and lid, with the wafer, substrate and adhesive stack ready for bonding.

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- Fast Efficient Bonding
- Controlled Bond line
- No Messy Wax
- Operator Independent
- Simple Operation

DXB Wafer Bonder Specifications

- Bonding Chamber Size
 - DXB-525-01 5.2 inches (132 mm)
 - DXB-525-02 5.2 inches (132 mm)
 - DXB-120-01 11 inches (279 mm)
 - DXB-120-03 11 inches (279 mm)
- Temperature Range: 100-320° F (40-160° C)
- Cycle Time Range: 1 sec –10 min
- Power Required
 - DXB-525-02 220/240 VAC 2.5 amp, 50/60Hz
 - DXB-525-01 100/120 VAC 5 amp, 50/60Hz
 - DXB-120-02 220/240 VAC 5 amp, 50/60Hz
 - DXB-120-01 100/120 VAC 10 amp, 50/60Hz
- Vacuum Required: 18 in Hg
- Environmental: 60-80° F (15-27° C), 0-95 % Humidity (non-condensing)
- Dimensions

DXB-525-XX	Height	7 in (180 mm)
	Width	9 in (225 mm)
	Depth	11.5 in (290 mm)
	Chuck	5.25 in (135 mm)
DXB-120-XX	Height	8 in (200 mm)
	Width	15 in (375 mm)
	Depth	17.5 in (440 mm)
	Chuck	11.25 in (285 mm)



5577 Skylane Boulevard
 Santa Rosa, CA 95403
 Phone: 707.542.4227
 Fax: 707.579.8599
www.dynatex.com
sales@dynatex.com

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